

Contents

| | | |
|---|---|---|
| 1 | SSOP16 Package | 2 |
| 2 | Temperature Profile..... | 3 |
| 3 | Storage Conditions..... | 3 |
| 4 | Recommended Printed Circuit Board (PCB) Footprint | 4 |
| 5 | Related Documents..... | 4 |
| 6 | Glossary | 5 |
| 7 | Document Revision History..... | 5 |

List of Figures

| | | |
|------------|--------------------------------|---|
| Figure 1.1 | Package View | 2 |
| Figure 4.1 | Recommended PCB Footprint..... | 4 |

List of Tables

| | | |
|-----------|--------------------------|---|
| Table 1.1 | Package Dimension..... | 2 |
| Table 1.2 | Package Marking | 3 |
| Table 3.1 | Storage Conditions | 3 |

1 SSOP16 Package

The standard package of the ZSC31050 is a SSOP16 (5.3mm body width) with lead-pitch 0.65mm. Refer to the *ZSC31050 Data Sheet* for pin assignments.

Weight: ≤ 0.3 g

Package Body Material: Low-stress epoxy

Lead Material: FeNi-Alloy or Cu-Alloy

Lead Finish: solder plating

Lead Form: Z-bends

Figure 1.1 Package View

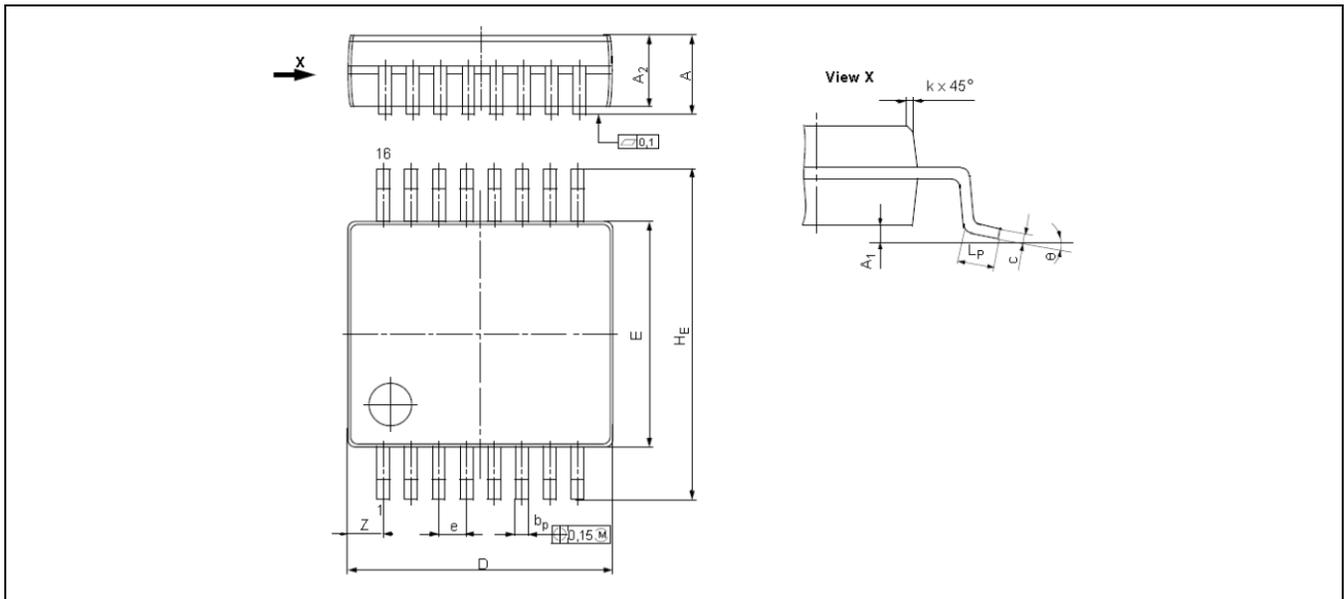


Table 1.1 Package Dimension

| Package Dimensions | | | | | |
|--------------------|-------|----------------------|-------|-------------------|-------|
| Dimension | Value | Dimension | Value | Dimension | Value |
| A _{max} | 1.99 | C _{min} | 0.09 | H _{Emin} | 7.65 |
| A _{min} | 1.73 | C _{max} | 0.20 | H _{Emax} | 7.90 |
| A1 _{min} | 0.05 | D _{min} * | 6.07 | k _{min} | 0.25 |
| A1 _{max} | 0.21 | D _{max} * | 6.33 | LP _{min} | 0.63 |
| A2 _{min} | 1.68 | E _{min} * | 5.20 | Z _{max} | 0.89 |
| A2 _{max} | 1.78 | E _{max} * | 5.38 | θ _{min} | 0° |
| b _{Pmin} | 0.25 | e _{nom} | 0.65 | θ _{max} | 10° |
| b _{Pmax} | 0.38 | * without mold-flash | | | |

Table 1.2 Package Marking

| Top Side | | Comments |
|----------------------|------------|--|
| 1 st Line | ZMDI | |
| 2 nd Line | 31050%\$G1 | % = Revision Identifier; \$ = Temperature Range Identifier; examples: ZSC31050FEG1, ZSC31050FAG1; ZSC31050FIG1 |
| 3 rd Line | YYWW | Package Assembly Date: YEAR,YEAR,WEEK,WEEK |

2 Temperature Profile

Refer to calculation sheet *ZMDI Temperature Profile Calculation Sheet* for details.

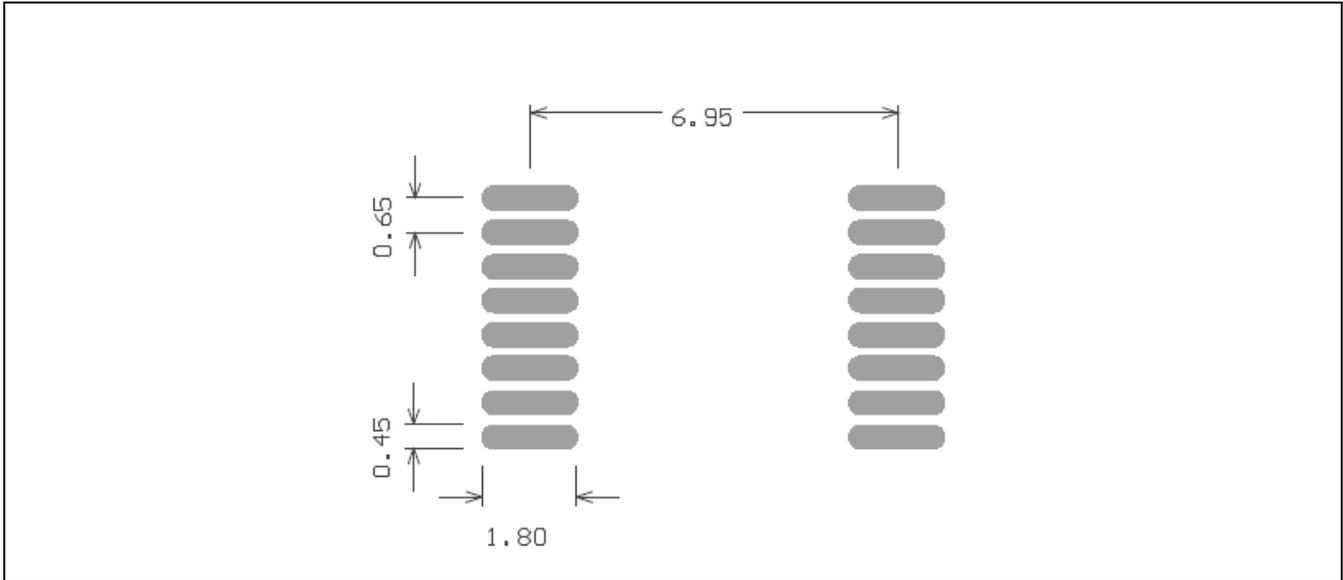
3 Storage Conditions

Table 3.1 Storage Conditions

| Parameter | Min | Typ | Max | Unit | Conditions |
|--|-----|-----|-----|--------|---|
| t _{Storage} , Dry Pack | | | 36 | months | Outside of the dry pack: ≤ 40°C temperature and ≤ 90% relatively humidity |
| t _{Storage} , Tape/Reel (Without Dry Pack) | | | 24 | months | -10°C to 50°C and storage at a relative humidity with no condensation Important: Drying before assembly is required. |
| t _{Storage} , Tape/Reel (Without Dry Pack) | | | 168 | hours | ≤ 30°C temperature and ≤ 60% relatively humidity |

4 Recommended Printed Circuit Board (PCB) Footprint

Figure 4.1 Recommended PCB Footprint



5 Related Documents

| Document |
|--|
| ZSC31050 Feature Sheet |
| ZSC31050 Data Sheet |
| IDT Temperature Profile Calculation Sheet |
| ZSC31050 Technical Note – Die Dimensions and Pad Locations * |

Visit the ZSC31050 product page (www.IDT.com/ZSC31050) or contact your nearest sales office for the latest version of these documents.

* Documents marked with an asterisk (*) are available on request only.

6 Glossary

| Term | Description |
|------|------------------------------|
| SSC | Sensor Signal Conditioner |
| SSOP | Shrink Small Outline Package |

7 Document Revision History

| Revision | Date | Description |
|----------|------------------|--|
| 1.00 | May 16, 2013 | First release of document as combined die and package information technical note. |
| 1.10 | October 15, 2015 | Separation of document into separate technical notes for die dimensions and for SSOP16 dimensions. Update for contact information and imagery for cover and headings. |
| | April 26, 2016 | Changed to IDT branding. |

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